



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-18
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3H100UFY	AB6Y*ZC5PB3V	A	BO2A	2016-11-18
Amount		UoM	Unit type	ST ECOPACK Grade
50.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	3.75 - 4.3 - 0.98	2	J bend	
Comment	Package: SMB Flat NEP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AB6Y*ZCSPB3V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.938	mg	supplier	die	Silicon (Si)	7440-21-3		0.867	mg	924307	17340
				supplier	metallization	Aluminium (Al)	7429-90-5		0.042	mg	44776	840
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1066	20
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1066	20
				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	5330	100
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.006	mg	6397	120
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1066	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	7463	140
				supplier	polymer die coating	Durimide	proprietary		0.008	mg	8529	160
				Leadframe	Copper & its alloys	19.346	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.009	mg	465	180
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.016	mg	827	320
supplier	alloy	Lead (Pb)	7439-92-1					7a-Lead in high me	0.971	mg	955709	19420
Soft solder	Solder	1.016	mg	JIG R	solder	Silver (Ag)	7440-22-4		0.025	mg	24606	500
				supplier	solder	Tin (Sn)	7440-31-5		0.02	mg	19685	400
				supplier	wire	Copper (Cu)	7440-50-8		0.145	mg	1000000	2900
Encapsulation	Other Organic Materials	27.825	mg	supplier	mold compound	Silica, vitreous	60676-86-0		24.347	mg	875004	486940
				supplier	mold compound	Epoxy Resin	85954-11-6		1.113	mg	40000	22260
				supplier	mold compound	Epoxy resin A	25068-38-6		1.113	mg	40000	22260
				supplier	mold compound	Phenol Resin	26834-02-6		1.113	mg	40000	22260
				supplier	mold compound	Carbon black	1333-86-4		0.139	mg	4996	2780
Connections coating	Solder	0.73	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.73	mg	1000000	14600